## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Young Hoon PARK, et al.	)
Serial No.:	10/511,883	) Group Art Unit: 1763
Filed:	October 19, 2004	) Examiner: ) NG, James Wai Heung )
For:	APPARATUS AND METHOD FOR DEPOSITING THIN FILM ON WAFER USING REMOTE PLASMA	

## REPLY TO NON-FINAL OFFICE ACTION UNDER 37 CFR 1.111, WITH AMENDMENT

VIA EFS Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

In response to the Office Action mailed January 10, 2008, Applicants request reconsideration in view of the following amendments and remarks for entry in the above-identified application.

Amendments to the Claims begin on page 2 of this paper; and

Remarks begin on page 8 of this paper.

YPL-0108 IP-18852